

ON Semiconductor **10/15/2019**

Base Part		FDB120N10		
Orderable Part		FDB120N10		Total weight (mg) 1485.898
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	12.3	Silicon (Si)	7440-21-3	100
Die Attach Solder	7.33	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	860.318	Tin (Sn)	7440-31-5	0.13
		Nickel (Ni)	7440-02-0	0.26
		Copper (Cu)	7440-50-8	99.61
Mold Compound-Black	595.8	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	1.99731454
		Ortho Cresol Novolac Resin	29690-82-2	27.52601544
		Antimony Trioxide (Sb2O3)	1309-64-4	3.00436388
		Carbon Black (C)	1333-86-4	0.99865727
		Fused Silica (SiO2)	60676-86-0	66.47364888
Plating	5.52	Tin (Sn)	7440-31-5	100
Wire Bond - Al	4.63	Aluminum (Al)	7429-90-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>